

TUNG &
ASSOCIATES
Intellectual Property Law

Date: Jan. 16, 2003

TO: Examiner Richard A. Booth (703) 872-9319
Art Unit: 2812

FAX Operator: Kathy Dixon

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Subject Matter: 09/ 920,911 Attorney Doc: 67,200-506

Message:

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Total number of pages sent: - **13** - (including this cover sheet)

67,200-506; TSMC 00-804
Serial Number 09/920,911

#6
Response
D. Smalls-Logan
1-28-03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

TO: ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

FROM: Tung & Associates
838 West Long Lake Road - Suite 120
Bloomfield Hills, MI 48302

DATE: 14 January 2003

REF: Applicant : Yu et al. Filing Date : 2 August 2001
Serial No : 09/920,911 Att'y No. : 67,200-506
Art Unit : 2812 Examiner : Richard A. Booth
Title : Thermal Compensation Method for Forming Semiconductor
Integrated Circuit Microelectronic Fabrication

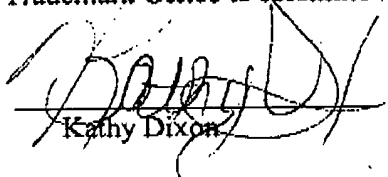
RESPONSE TO OFFICE ACTION MADE FINAL

Sir:

In response to an office action mailed on 20 December 2002 and made FINAL,
please consider the following remarks pertaining to the above referenced application.

CERTIFICATE OF FACSIMILE

I hereby certify that this correspondence is being facsimile transmitted to the United States
Patent and Trademark Office to facsimile number 703-872-9319 on the date below:


Kathy Dixon

1/16/03
Date

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